



FlipChip International and IC Interconnect Announce U.S. Sales and Marketing Agreement for Wafer Level Packaging Services.

Phoenix AZ/Colorado Springs CO, October 26, 2009 – FlipChip International, (FCI), the global technology leader in flip-chip bumping and Wafer Level Packaging and IC Interconnect (ICI), a TS16949 registered leader in electroless Nickel flip-chip bumping and Wafer Level Packaging announced today a U.S. joint Sales and Marketing agreement. This agreement allows their respective U.S. customers access to the extensive service portfolios of both FCI and ICI.

FCI will continue to provide turn-key Wafer Level Packaging services in the U.S. and electroless Nickel bumping in China at its FCMS Joint Venture. ICI will continue its US and Asian operations based on electroless Nickel bumping and stencil printed solder paste services.

Both companies will work with existing and new customers to offer the optimum technology for the particular demands of each application in the coming generations of packaging to be utilized in mobile handsets, medical devices, automotive integrated circuits, microprocessors, graphics processors, and wireless 3G integrated solutions. This agreement will not impact any of the other alliances either company has formed.

“This outstanding strategic alliance confirms the strong relationship between two internationally recognized semiconductor providers and validates the global strategic importance of Wafer Level Packaging and flip-chip bumping for next generation products, including 3G mobile handsets,” said Bob Forcier, FCI President and CEO.

Curt Erickson, President of ICI, said, “We are excited to form this alliance with FCI, which leverages the strengths of two robust technology portfolios and provides the most comprehensive US bumping solutions available in the market today. In addition to bumping technologies, the alliance offers customers the potential of a one-stop solution for backend services in the USA and multiple migration pathways to Asia.

ICI is a privately held supplier of products and services for the wafer bumping and wafer scale packaging semiconductor market. ICI is wholly owned by Eagle Investment I-II, LLC a capital source dedicated to start-ups with 1 to 5 million dollar capitalization needs.

FCI is a privately held supplier of products and services for the wafer bumping and wafer level packaging market. FCI is a wholly owned subsidiary of RoseStreet Labs LLC, a supplier of products and services for the semiconductor, renewable energy and life sciences, markets.

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